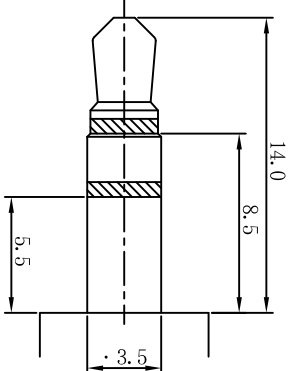
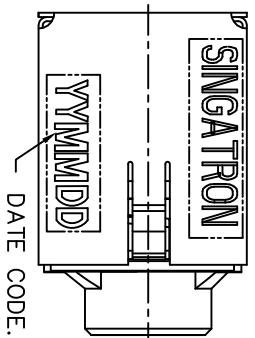
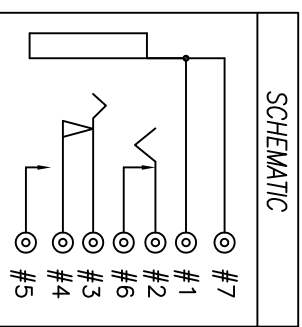


RECOMMEND PCB LAYOUT
TOP VIEW(TOL.±0.05)



RECOMMEND PLUG
3-POLE



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3Kg.
 - WITHDRAWAL FORCE: 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - METAL EARTH AND SHIELDING MUST BE CONDUCT.
 - PACKAGING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ☉
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: ☉
 - FOR LEAD-FREE PROCESS.

H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 60u"
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	120u" Sn ON SOLDER AREA
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	ALL OVER 50u" Ni
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA OVER 50u" Ni
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag20u" Min OVER Ni50u" Min.
B	EARTH	1	PHOSPHOR BRONZE 0.2t	Ag20u" Min OVER Ni20u" Min.
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singatron Enterprise Co., Ltd. 信音企業股份有限公司				
DECIMALS: ANGLES:				
X	±0.5	X	±2'	
X.X	±0.3	X.X	±1'	
X.XX	±0.2			
TITLE: 3.5φ PHONE JACK				
DWN	Owen	PART NO.2SI-S351-085F		
CHKD	Lussein	SCALE:4:1	UNIT: mm	
APVD	Max	SIZE: A3	SHEET: 1 OF 1	REV:A
CUSTOMER COPY				

REV/ECN NO OR DESCRIPTION	REVISED	DATE
A PDR NO.T110620-4A	Owen	2011.11.29